Status Report for SI to TSG

Study Item Name: Improvement of Inter-frequency and inter-system measurement for 1.28 Mcps TDD

SOURCE: Rapporteur   **TSG: RAN**   **WG: WG1**

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Ref. to SI sheet: RP-010929

Progress Report since the last TSG (for all involved WGs):

RAN1: RAN1 is the leading working group of this SI. The purpose of this SI is to specify some set of solutions in order to improve the inter-frequency and inter-system measurement capability for 1.28 Mcps TDD, particularly in terms of enlarging the measurement window. In the subsequent two RAN1 meeting, the discussion on TR [1] and three related paper [2][3][4] were made. The description of problem, scope and methods taking into account higher layer aspects needs to be revised. Moreover, liaison to RAN2, RAN3 and RAN 4 [5] was sent to investigate the impacts to other WG's specifications.

RAN2: In 26th meeting, the SI and corresponding signalling impact were clarified [10], [11]. However, there was no consensus on the signalling impact. An enhanced signalling method [12] was submitted in 27th meeting but there was no discussion due to the lack of time.

RAN3: For feasibility study in Iur/Iub areas, related contributions were submitted as [13] [14] at RAN3#27. But they were not treated because there was no enough time for release 5 study item.

RAN4: This SI has discussed in RAN4 #21[6][7]. The conclusion was made that this SI has no impact on current RAN4 specifications.

List of Completed elements (for complex work items):

RAN1: Overall structure of TR

RAN2: Clarification of the SI.

RAN3: No

RAN4: Agreement on the impact to the WG4 related specifications

List of open issues:

- Physical layer performance for high data rate support.
- Detailed signalling support for the measurement

Estimates of the level of completion (when possible):

30 %

SI completion date review resulting from the discussion at the working group:
TSG RAN #16 (June 2002)

References to WG's internal documentation and/or TRs:

[1] 3GPP TSGR1-01-0468, "Revised draft TR 25.888 on Improvement of Inter-frequency and inter-system measurement for 1.28Mcps TDD," (Revised version of Tdoc R1-02-0149), Samsung Electronics, Feb. 2002.

[2] 3GPP TSGR1-02-0236, "Improvement of monitoring FDD from 1.28Mcps TDD," (Revised version of Tdoc R1-02-0099), Samsung Electronics, Feb. 2002.

[3] 3GPP TSGR1-02-0237, "Improvement of monitoring 3.84 Mcps TDD from 1.28Mcps TDD," (Revised version of Tdoc R1-02-0100), Samsung Electronics, Feb. 2002.

[4] 3GPP TSGR1-02-0238, "Improvement of monitoring 1.28 Mcps TDD from 1.28Mcps TDD," (Revised version of Tdoc R1-02-0101), Samsung Electronics, Feb. 2002.

[5] 3GPP TSGR3-02-0256, Skeleton TR3-011 v001, Samsung Electronics, Jan. 2002.

[6] 3GPP TSGR3-02-0659, "Signalling support for improvement of inter-RAT measurements," Samsung Electronics, Feb. 2002.

[7] 3GPP TSGR4-020082, "LS on improvement of inter-frequency and inter-system measurement for 1.28 Mcps TDD," Samsung Electronics, Jan. 2002.

[8] 3GPP TSGR4-020010, "Introduction of Improvement of Inter-frequency and Inter-system Measurement for 1.28 Mcps TDD", Samsung Electronics, Jan. 2002.

[9] 3GPP TSGR4-020010, "Analysis of an impact on TS 25.123 due to Improvement of Inter-frequency and Inter-system Measurement for 1.28 Mcps TDD", Samsung Electronics, Jan. 2002.

[10] 3GPP TSGR2-020119, "Introduction of TR 25.xxx on Improvement of Inter-frequency and inter-system measurement (TSG RAN WG1)", Samsung Electronics, Jan. 2002.

[11] 3GPP TSGR2-020077, "Improvement of Inter-RAT measurement for 1.28Mcps TDD", Samsung Electronics, Jan. 2002.

[12] 3GPP TSGR2-020387, "Signalling support for improvement of inter-RAT measurement for 1.28Mcps TDD", Samsung Electronics, Jan. 2002.

[13] 3GPP TSGR3-020256, "Skeleton TR3-001 v001", Samsung Electronics, Feb. 2002

[14] 3GPP TSGR3-020659, "Signalling support for improvement of inter-RAT measurements", Samsung Electronics, Feb. 2002